

30mA, 40V Schottky Barrier Diode

FEATURES

- Low reverse current
- Surface mount device type
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Adapters
- For switching power supply
- Low stored charge
- Inverter

MECHANICAL DATA

- Case: SOD-523F
- Molding compound meets UL 94 V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: Indicated by cathode band
- Weight: 1.60 mg (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	30	mA	
V _{RRM}	40	V	
V _F at I _F = 1mA	0.37	V	
T _{J MAX}	125	°C	
Package	SOD-523F		
Configuration	Single die		







SOD-523F



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)			
PARAMETER	SYMBOL	RB 751M5-40	UNIT
Marking code on the device		5	
Repetitive peak reverse voltage	V _{RRM}	40	V
DC block voltage	V _R	30	V
Forward current	I _F	30	mA
Non-repetitive peak forward surge current @ t = 8.3ms	I _{FSM}	0.2	А
Power dissipation	PD	200	mW
Junction temperature range	TJ	-55 to +125	°C
Storage temperature range	T _{STG}	-55 to +125	°C



ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage ⁽¹⁾	$I_{F} = 1mA, T_{J} = 25^{\circ}C$	V _F	-	0.37	V
Reverse current ⁽²⁾	$V_{R} = 30V, T_{J} = 25^{\circ}C$	I _R	-	0.50	μA
Capacitance	$V_{R} = 1V, f = 1MHz$	С	2	-	pF

Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

ORDERING INFORMATION		
ORDERING CODE	PACKAGE	PACKING
RB751M5-40 RSG	SOD-523F	8K / 7" Reel



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

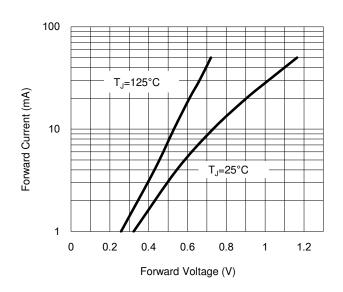


Fig.1 Typical Forward Characteristics

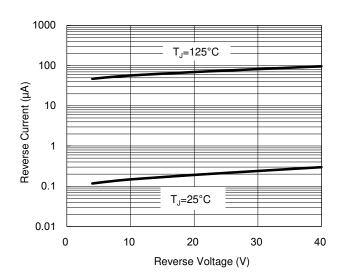


Fig.2 Typical Reverse Characteristics

Fig.4 Power Derating Curve

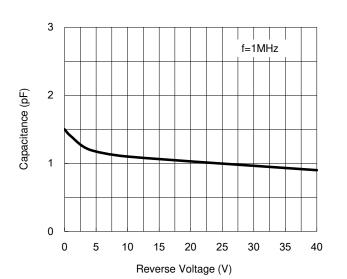
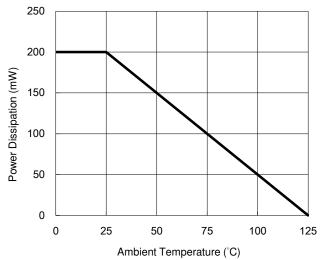


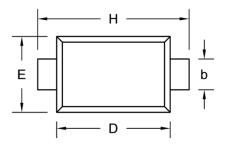
Fig.3 Typical Capacitance Characteristics



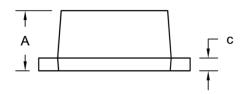


PACKAGE OUTLINE DIMENSION

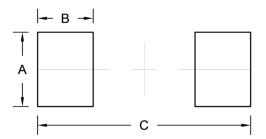
SOD-523F



DIM. Unit ((mm)	Unit	Unit (inch)	
	Min.	Max.	Min.	Max.	
A	0.50	0.77	0.020	0.030	
b	0.25	0.40	0.010	0.016	
с	0.07	0.20	0.003	0.008	
D	1.10	1.30	0.043	0.051	
E	0.70	0.90	0.028	0.035	
н	1.50	1.70	0.059	0.067	



SUGGEST PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	0.80	0.031
В	0.60	0.024
С	2.30	0.091



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